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We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



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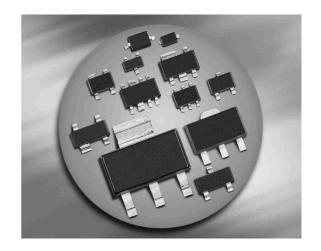




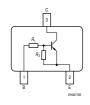
PNP Silicon Digital Transistor

- Switching circuit, inverter, interface circuit, driver circuit
- Built in bias resistor (R_1 = 4.7k Ω , R_2 = 4.7k Ω)
- Pb-free (RoHS compliant) package
- Qualified according AEC Q101





BCR162



Туре	Marking	Pin Configuration			Package			
BCR162	WUs	1=B	2=E	2=C	-	-	-	SOT23

Maximum Ratings

Symbol	Value	Unit	
V _{CEO}	50	V	
V_{CBO}	50		
V _{i(fwd)}	30		
V _{i(rev)}	10		
I _C	100	mA	
P _{tot}	200	mW	
$T_{\rm j}$	150	°C	
T _{stq}	-65 150		
	V _{CEO} V _{CBO} V _{i(fwd)} V _{i(rev)} I _C P _{tot}	$V_{\rm CEO}$ 50 $V_{\rm CBO}$ 50 $V_{\rm i(fwd)}$ 30 $V_{\rm i(rev)}$ 10 $I_{\rm C}$ 100 $P_{\rm tot}$ 200	

Thermal Resistance

Parameter	Symbol	Value	Unit
Junction - soldering point ¹⁾	R _{thJS}	≤ 240	K/W

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2011-08-29



Electrical Characteristics at $T_A = 25$ °C, unless otherwise specified

Symbol		Values			
		typ.	max.		
1 1		ı	1		
V _{(BR)CEO}	50	-	-	V	
V _{(BR)CBO}	50	-	-		
I _{CBO}	-	-	100	nA	
I _{EBO}	-	-	1.61	mA	
h _{FE}	20	-	-	-	
V _{CEsat}	-	-	0.3	V	
$V_{i(off)}$	8.0	-	1.5		
V _{i(on)}	1	-	2.5		
, ,					
R ₁	3.2	4.7	6.2	kΩ	
R_1/R_2	0.9	1	1.1	_	
•		<u>· </u>	•	<u>. </u>	
f _T	-	200	_	MHz	
C _{cb}	-	3	-	pF	
	V(BR)CEO V(BR)CBO ICBO IEBO Vi(off) Vi(on) R1 R1/R2	Min. V(BR)CEO 50 V(BR)CBO 50 ICBO - IEBO - VCEsat - Vi(off) 0.8 Vi(on) 1 R1 3.2 R1/R2 0.9 fT -	min. typ. V(BR)CEO 50 - V(BR)CBO 50 - ICBO - - IEBO - - VCEsat - - Vi(off) 0.8 - Vi(on) 1 - R1 3.2 4.7 R1/R2 0.9 1 fT - 200	min. typ. max. V(BR)CEO 50 - - V(BR)CBO 50 - - ICBO - - 100 IEBO - - 1.61 VCEsat - - 0.3 Vi(off) 0.8 - 1.5 Vi(on) 1 - 2.5 R1 3.2 4.7 6.2 R1/R2 0.9 1 1.1	

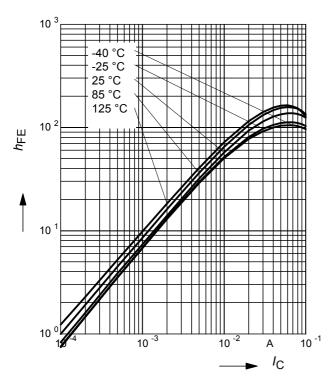
 $^{^{1}}$ For calculation of R_{thJA} please refer to Application Note AN077 (Thermal Resistance Calculation)

 $^{^{2}}$ Pulse test: t < 300 μ s; D < 2%



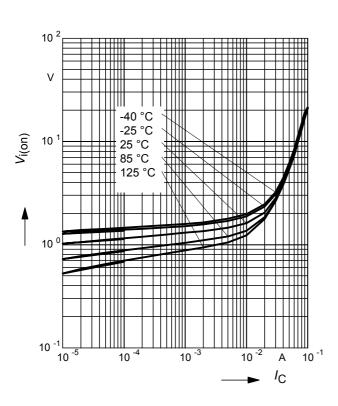
DC current gain $h_{FE} = f(I_C)$

 V_{CE} = 5 V (common emitter configuration)



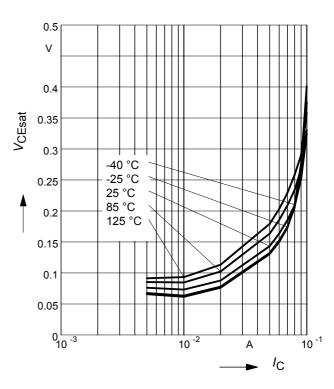
Input on Voltage $Vi_{(on)} = f(I_C)$

 V_{CE} = 0.3V (common emitter configuration)



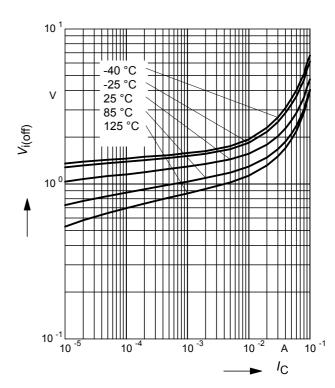
Collector-emitter saturation voltage

 $V_{CEsat} = f(I_{C}), I_{C}/I_{B} = 20$



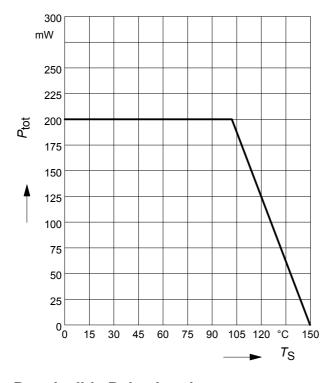
Input off voltage $V_{i(Off)} = f(I_C)$

 V_{CE} = 5V (common emitter configuration)

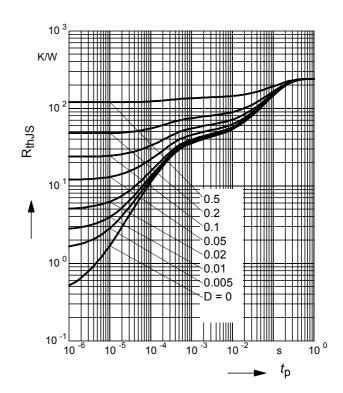




Total power dissipation $P_{tot} = f(T_S)$ BCR162



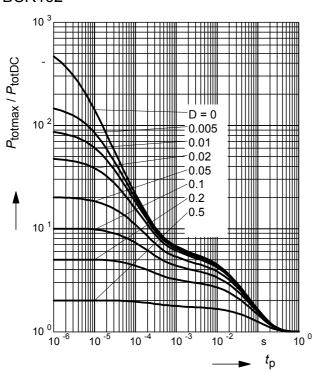
Permissible Pulse Load $R_{thJS} = f(t_p)$ BCR162



Permissible Pulse Load

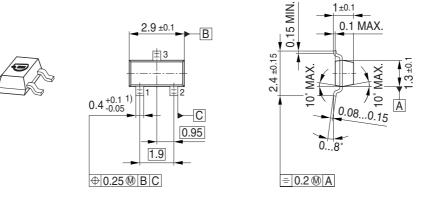
$$P_{\text{totmax}}/P_{\text{totDC}} = f(t_{\text{p}})$$

BCR162



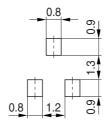


Package Outline

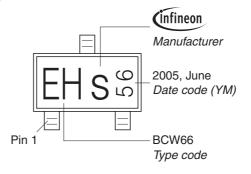


1) Lead width can be 0.6 max. in dambar area

Foot Print

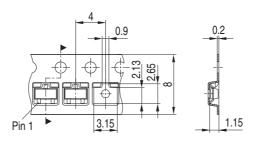


Marking Layout (Example)



Standard Packing

Reel ø180 mm = 3.000 Pieces/Reel Reel ø330 mm = 10.000 Pieces/Reel



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